



40V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)} max	I _D T _A = +25°C
40)/	60mΩ @ V _{GS} = -10V	-6.4A
-40V	100mΩ @ V _{GS} = -4.5V	-5.6A

Features and Benefits

- Low On-Resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Description and Applications

This new generation of Trench MOSFETs utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, and power management applications.

- DC-DC Converters
- Disconnect Switches
- Audio Output Stages
- Motor Control

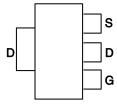
Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208
- Weight: 0.112 grams (Approximate)

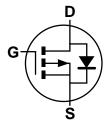
SOT223



Top View



Pin Out - Top View



Equivalent Circuit

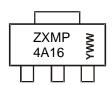
Ordering Information (Note 5)

Product	Case	Packaging
ZXMP4A16GQTA	SOT223	1,000/Tape & Reel
ZXMP4A16GQTC	SOT223	4,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



ZXMP4A16 = Product Type Marking Code YWW = Date Code Marking Y = Year (ex: 4 = 2014) WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	-40	V	
Gate-Source Voltage		V_{GS}	±20	V	
		(Note 7)		-6.4	
Continuous Drain Current	$V_{GS} = 10V$	$T_A = +70^{\circ}C \text{ (Note 7)}$	I _D	-4.6	Α
		(Note 6)		-1.7	
Pulsed Drain Current	V _{GS} = 10V	(Note 8)	I _{DM}	-21	Α
Continuous Source Current ((Body diode)	(Note 7)	I _S	-5.2	Α
Pulsed Source Current (Bod	y diode)	(Note 8)	I _{SM}	-21	Α

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 6)	0	2.0 16	W	
Linear Derating Factor	(Note 7)	P _D	3.9 31	mW/°C	
Thermal Decistores, Junction to Ambient	(Note 6)	-	62.5	°C/W	
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{\theta JA}$	32.2	C/VV	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C	

Electrical Characteristics @TA = 25°C unless otherwise specified

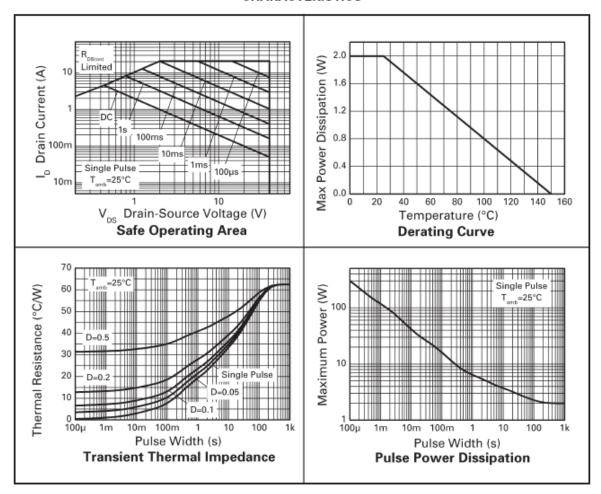
Characteristic	Symbol	Min	Тур	Max	Unit	Tost C	ondition
OFF CHARACTERISTICS	Symbol	141111	iyp	WIGA	Onit	1631 0	Jiidition
Drain-Source Breakdown Voltage	BV _{DSS}	-40		_	V	I _D = -250μA, V _{GS} = 0V	
Zero Gate Voltage Drain Current				-1	μA		
	I _{DSS}		_			V _{DS} = -40V, V _{GS} =	
Gate-Source Leakage	I _{GSS}		_	100	nA	$V_{GS} = \pm 20V, V_{DS} =$: 0V
ON CHARACTERISTICS			1	1	1		
Gate Threshold Voltage	V _{GS(th)}	-1.0	_	_	V	$I_D = -250\mu A$, $V_{DS} =$: V _{GS}
Static Drain-Source On-Resistance (Note 9)	R _{DS (ON)}			0.060	Ω	V _{GS} = -10V, I _D = -3.8A	
Otalic Brain Gource On Nesistance (Note 5)	NDS (ON)			0.100	32	V _{GS} = -4.5V, I _D = -2.9A	
Forward Transconductance (Notes 9 & 11)	g fs	_	8.85	_	S	V _{DS} = -15V, I _D = -3.8A	
Diode Forward Voltage (Note 9)	V_{SD}	_	-0.85	-1.2	V	$T_J = 25^{\circ}C$, $I_S = -3.4A$, $V_{GS} = 0V$	
Reverse Recovery Time (Note 11)	t _{rr}		27.2	_	ns	T _J = +25°C , I _F = -3A, di/dt= 100A/μs	
Reverse Recovery Charge (Note 11)	Qrr	_	25.4	_	nC		
DYNAMIC CHARACTERISTICS (Note 11)							
Input Capacitance	C _{iss}	_	1007	_	pF	V _{DS} = -20V, V _{GS} = 0V -f= 1MHz	
Output Capacitance	Coss	_	130	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	85	_	pF		
Total Gate Charge (Note 10)	Qg	_	13.6	_	nC	V _{GS} = -5V	
Total Gate Charge (Note 10)	Qg	_	26.1	_	nC	V _{DS} = -20V V _{GS} = -10V I _D = -3.8A	
Gate-Source Charge (Note 10)	Q _{gs}	_	2.8	_	nC		
Gate-Drain Charge (Note 10)	Q _{gd}	_	4.8	_	nC		
Turn-On Delay Time (Note 10)	t _{D(on)}	_	3.0	_	ns	$V_{DD}\text{= -20V, }V_{GS}\text{= -10V,}$ $I_{D}\text{= -1A, }R_{G}\cong 6.0\Omega$	
Turn-On Rise Time (Note 10)	t _r	_	3.5	_	ns		
Turn-Off Delay Time (Note 10)	t _{D(off)}	_	13.4	_	ns		
Turn-Off Fall Time (Note 10)	t _f	_	7.2	_	ns		

Notes:

- 6. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- To ra device surface mounted on FR4 PCB measured at t ≤ 10 seconds.
 For a device surface mounted on FR4 PCB measured at t ≤ 10 seconds.
 For a device surface mounted on 25mm x 25mm FR4 PCB, D= 0.05 pulse width limited by maximum junction temperature.
 Measured under pulsed conditions. Width ≤ 300µs. Duty cycle ≤ 2%.
- 10. Switching characteristics are independent of operating junction temperature.
- 11. For design aid only, not subject to production testing.

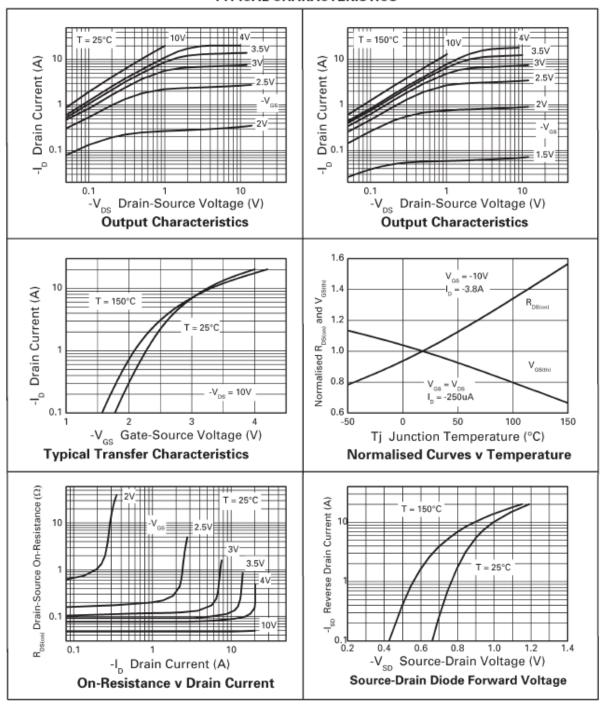


CHARACTERISTICS

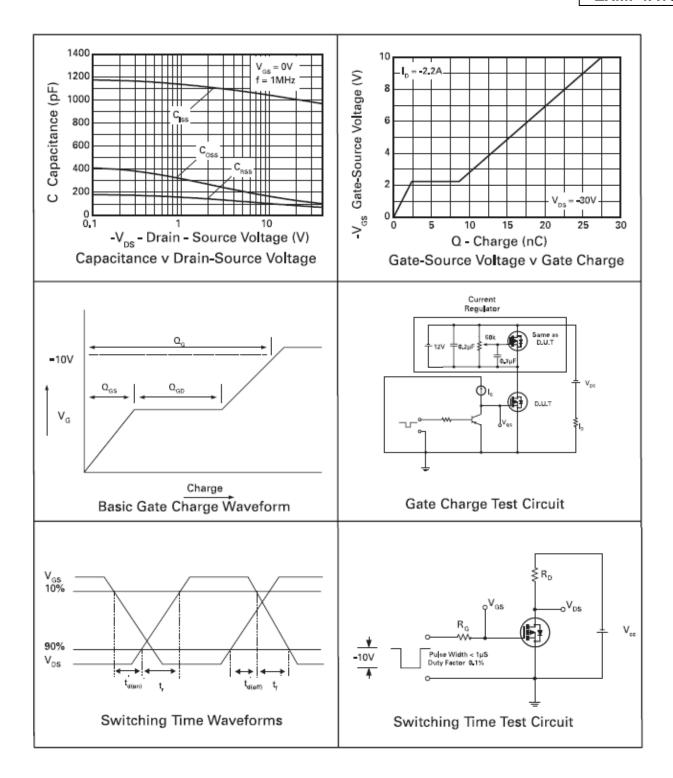




TYPICAL CHARACTERISTICS



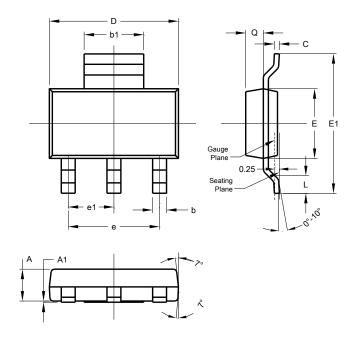






Package Outline Dimensions

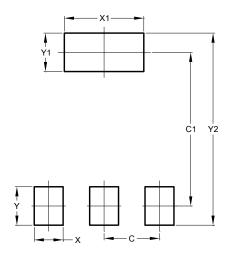
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



SOT223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A1	0.010	0.15	0.05		
b	0.60	0.80	0.70		
b1	2.90	3.10	3.00		
С	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	-	-	4.60		
e1	-	-	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Υ	1.60
Y1	1.60
Y2	8.00



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2015, Diodes Incorporated

www.diodes.com